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BMX055

Small, versatile 9-axis sensor module

Bosch Sensortec



BOSCH

Invented for life



BMX055: Data sheet

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Notes

Data and descriptions within this document are subject to change without notice.

Product photos and pictures are for illustration purposes only and may differ from the real product's appearance.

BMX055

Basic Description

Key features

- 3 sensors in one device
 - Small package
 - Common voltage supplies
 - Digital interface
 - Smart operation and integration
 - Consumer electronics suite
- an advanced triaxial 16bit gyroscope, a versatile, leading edge triaxial 12bit accelerometer and a full performance geomagnetic sensor
LGA package 20 pins
footprint 3.0 x 4.5 mm², height 0.95mm
V_{DD} voltage range: 2.4V to 3.6V
SPI (4-wire, 3-wire), I²C, 4 interrupt pins
V_{DDIO} voltage range: 1.2V to 3.6V
All sensors can be operated individually
9-axis FusionLib software compatible
MSL1, RoHS and RoHS2 compliant, halogen-free
Operating temperature: -40°C ... +85°C

Accelerometer features

- Programmable functionality
 - On-chip FIFO
 - On-chip interrupt controller
 - On-chip temperature sensor
 - Ultra-low power IC
- Acceleration ranges $\pm 2g/\pm 4g/\pm 8g/\pm 16g$
Low-pass filter bandwidths 1kHz - <8Hz
Integrated FIFO with a depth of 32 frames
Motion-triggered interrupt-signal generation for
 - new data
 - any-motion (slope) detection
 - tap sensing (single tap / double tap)
 - orientation- & motion inactivity recognition
 - flat/low-g/high-g detectionfactory trimmed, 8-bit, typical slope 0.5K/LSB.
130 μ A current consumption, 1.3ms wake-up time, advanced features for system power management

Gyroscope features

- Programmable functionality
 - On-chip FIFO
 - On-chip interrupt controller
 - Low power IC
- Ranges switchable from $\pm 125^\circ/s$ to $\pm 2000^\circ/s$
Low-pass filter bandwidths 230Hz - 12Hz
Fast and slow offset controller (FOC and SOC)
Integrated FIFO with a depth of 100 frames
Motion-triggered interrupt-signal generation for
 - new data
 - any-motion (slope) detection
 - high rate< 5mA current consumption, 30ms start-up time
wake-up time in fast power-up mode only 10ms

Magnetometer features

- Flexible functionality
Magnetic field range typical 1300 μ T (x-, y-axis);
 \pm 2500 μ T (z-axis)
Magnetic field resolution of \sim 0.3 μ T
- On-chip interrupt controller
Interrupt-signal generation for
 - new data
 - magnetic low-/high-threshold detection
- Ultra-low power
Low current consumption (170 μ A @ 10Hz in low power preset), short wake-up time, advanced features for system power management

Typical applications

- Advanced gaming, HMI and augmented reality
- Advanced gesture recognition
- Indoor navigation
- Tilt measurement and compensation
- Free-fall detection and drop detection for warranty logging
- Display profile switching
- Advanced system power management for mobile applications
- Menu scrolling, tap / double tap sensing

General description

The BMX055 is an integrated 9-axis sensor for the detection of movements and rotations and magnetic heading. It comprises the full functionality of a triaxial, low-g acceleration sensor, a triaxial angular rate sensor and a triaxial geomagnetic sensor.

The BMX055 senses orientation, tilt, motion, acceleration, rotation, shock, vibration and heading in cell phones, handhelds, computer peripherals, man-machine interfaces, virtual reality features and game controllers.

Advanced evaluation circuitry (ASIC) converts the outputs of the micro-electromechanical and geomagnetic sensing structures (MEMS), developed, produced and tested in BOSCH facilities. The programmable on-chip interrupt engine enables motion-based applications without use of a microcontroller by providing contextual status of accelerometer, gyroscope and geomagnetic sensor. The integrated FIFO memories allow buffering the inertial sensor data.

The corresponding chip-sets are integrated into one single 20-pin LGA 3.0mm x 4.5mm x 0.95 mm housing. For optimum system integration the BMX055 is equipped with digital bi-directional SPI and I²C interfaces. To provide maximum performance and reliability each device is tested and ready-to-use calibrated.

Package and interfaces of the BMX055 have been defined to match a multitude of hardware requirements. Since the sensor features a small footprint, a flat package and very low power consumption it is ideally suited for mobile-phone and tablet PC applications.

The BMX055 offers a variable V_{DDIO} voltage range from 1.2V to 3.6V and can be programmed to optimize functionality, performance and power consumption in customer specific applications.

Index of Contents

BASIC DESCRIPTION	2
1 SPECIFICATION	10
1.1 ELECTRICAL SPECIFICATION.....	10
1.2 ELECTRICAL AND PHYSICAL CHARACTERISTICS, MEASUREMENT PERFORMANCE.....	11
2 ABSOLUTE MAXIMUM RATINGS.....	20
3 BLOCK DIAGRAM.....	21
4 BASIC POWER MANAGEMENT	22
5 FUNCTIONAL DESCRIPTION ACCELEROMETER	23
5.1 ACCELERATION DATA	23
5.2 IMU DATA ACCELEROMETER	27
5.2.1 ACCELERATION DATA	27
5.2.2 TEMPERATURE SENSOR.....	28
5.3 SELF-TEST ACCELEROMETER.....	29
5.4 OFFSET COMPENSATION ACCELEROMETER.....	30
5.4.1 FAST COMPENSATION	31
5.4.2 FAST COMPENSATION	31
5.4.3 MANUAL COMPENSATION.....	32
5.4.4 INLINE CALIBRATION	32
5.5 NON-VOLATILE MEMORY ACCELEROMETER	33
5.6 INTERRUPT CONTROLLER ACCELEROMETER.....	33
5.6.1 GENERAL FEATURES.....	34
5.6.2 MAPPING TO PHYSICAL INTERRUPT PINS (INTTYPE TO INT PIN#)	35
5.6.3 ELECTRICAL BEHAVIOR (INT PIN# TO OPEN-DRIVE OR PUSH-PULL)	35
5.6.4 NEW DATA INTERRUPT	36
5.6.5 SLOPE / ANY-MOTION DETECTION	36
5.6.6 TAP SENSING.....	37
5.6.7 ORIENTATION RECOGNITION.....	39
5.6.8 FLAT DETECTION.....	43
5.6.9 LOW-G INTERRUPT.....	44
5.6.10 HIGH-G INTERRUPT	45
5.6.11 NO-MOTION / SLOW MOTION DETECTION.....	45
5.7 SOFTRESET ACCELEROMETER	47
6 REGISTER DESCRIPTION ACCELEROMETER	48
6.1 GENERAL REMARKS ACCELEROMETER	48
6.2 REGISTER MAP ACCELEROMETER.....	49

ACC REGISTER 0x00 (BGW_CHIPID)	50
ACC REGISTER 0x01 IS RESERVED.....	50
ACC REGISTER 0x02 (ACCD_X_LSB)	50
ACC REGISTER 0x03 (ACCD_X_MSB)	51
ACC REGISTER 0x04 (ACCD_Y_LSB)	51
ACC REGISTER 0x05 (ACCD_Y_MSB)	52
ACC REGISTER 0x06 (ACCD_Z_LSB).....	52
ACC REGISTER 0x07 (ACCD_Z_MSB).....	53
ACC REGISTER 0x08 (ACCD_TEMP).....	53
ACC REGISTER 0x09 (INT_STATUS_0).....	54
ACC REGISTER 0x0A (INT_STATUS_1)	54
ACC REGISTER 0x0B (INT_STATUS_2)	55
ACC REGISTER 0x0C (INT_STATUS_3)	56
ACC REGISTER 0x0D IS RESERVED	56
ACC REGISTER 0x0E (FIFO_STATUS).....	56
ACC REGISTER 0x0F (PMU_RANGE).....	57
ACC REGISTER 0x10 (PMU_BW)	57
ACC REGISTER 0x11 (PMU_LPW)	58
ACC REGISTER 0x12 (PMU_LOW_POWER)	58
ACC REGISTER 0x13 (ACCD_HBW)	59
ACC REGISTER 0x14 (BGW_SOFTRESET).....	60
ACC REGISTER 0x15 IS RESERVED.....	60
ACC REGISTER 0x16 (INT_EN_0)	60
ACC REGISTER 0x17 (INT_EN_1)	61
ACC REGISTER 0x18 (INT_EN_2)	61
ACC REGISTER 0x19 (INT_MAP_0)	62
ACC REGISTER 0x1A (INT_MAP_1)	62
ACC REGISTER 0x1B (INT_MAP_2)	63
ACC REGISTER 0x1C IS RESERVED	63
ACC REGISTER 0x1D IS RESERVED	63
ACC REGISTER 0x1E (INT_SRC)	63
ACC REGISTER 0x1F IS RESERVED	64
ACC REGISTER 0x20 (INT_OUT_CTRL)	64
ACC REGISTER 0x21 (INT_RST_LATCH)	65
ACC REGISTER 0x22 (INT_0)	65
ACC REGISTER 0x23 (INT_1)	66
ACC REGISTER 0x24 (INT_2)	66
ACC REGISTER 0x25 (INT_3)	66
ACC REGISTER 0x26 (INT_4)	67
ACC REGISTER 0x27 (INT_5)	67
ACC REGISTER 0x28 (INT_6)	68
ACC REGISTER 0x29 (INT_7)	69
ACC REGISTER 0x2A (INT_8).....	69
ACC REGISTER 0x2B (INT_9).....	70
ACC REGISTER 0x2C (INT_A)	70
ACC REGISTER 0x2D (INT_B)	71
ACC REGISTER 0x2E (INT_C)	71
ACC REGISTER 0x2F (INT_D)	72
ACC REGISTER 0x30 (FIFO_CONFIG_0).....	72
ACC REGISTER 0x31 IS RESERVED.....	73
ACC REGISTER 0x32 (PMU_SELF_TEST).....	73
ACC REGISTER 0x33 (TRIM_NVM_CTRL).....	73
ACC REGISTER 0x34 (BGW_SPI3_WDT)	74
ACC REGISTER 0x35 IS RESERVED.....	74
ACC REGISTER 0x36 (OFC_CTRL)	74
ACC REGISTER 0x37 (OFC_SETTING).....	75

ACC REGISTER 0x38 (OFC_OFFSET_X).....	76
ACC REGISTER 0x39 (OFC_OFFSET_Y).....	76
ACC REGISTER 0x3A (OFC_OFFSET_Z)	77
ACC REGISTER 0x3B (TRIM_GP0)	77
ACC REGISTER 0x3C (TRIM_GP1)	78
ACC REGISTER 0x3D IS RESERVED	78
ACC REGISTER 0x3E (FIFO_CONFIG_1)	78
ACC REGISTER 0x3F (FIFO_DATA).....	79

7 FUNCTIONAL DESCRIPTION GYROSCOPE..... 80

7.1 POWER MODES GYROSCOPE.....	80
7.1.1 ADVANCED POWER-SAVING MODES	81
7.2 BMX055 DATA GYROSCOPE	83
7.2.1 RATE DATA.....	83
7.3 ANGULAR RATE READ-OUT.....	84
7.4 SELF-TEST GYRO.....	84
7.5 OFFSET COMPENSATION GYROSCOPE	84
7.5.1 SLOW COMPENSATION	85
7.5.2 FAST COMPENSATION	85
7.5.3 MANUAL COMPENSATION.....	86
7.5.4 INLINE CALIBRATION	86
7.6 NON-VOLATILE MEMORY GYROSCOPE.....	86
7.7 INTERRUPT CONTROLLER GYROSCOPE.....	87
7.7.1 GENERAL FEATURES.....	87
7.7.2 MAPPING TO PHYSICAL INTERRUPT PINS (INTTYPE TO INT PIN#)	88
7.7.3 ELECTRICAL BEHAVIOUR (INT PIN# TO OPEN-DRIVE OR PUSH-PULL).....	88
7.7.4 NEW DATA INTERRUPT	88
7.7.5 ANY-MOTION DETECTION / INTERRUPT	89
7.7.6 HIGH-RATE INTERRUPT	90

8 REGISTER DESCRIPTION GYROSCOPE..... 91

8.1 GENERAL REMARKS	91
8.2 REGISTER MAP GYROSCOPE	92
GYR REGISTER 0x00 (CHIP_ID)	93
GYR REGISTER 0x01 IS RESERVED	93
GYR REGISTER 0x02 (RATE_X_LSB).....	93
GYR REGISTER 0x03 (RATE_X_MSB).....	94
GYR REGISTER 0x04 (RATE_Y_LSB).....	94
GYR REGISTER 0x05 (RATE_Y_MSB).....	95
GYR REGISTER 0x06 (RATE_Z_LSB).....	95
GYR REGISTER 0x07 (RATE_Z_MSB)	96
GYR REGISTER 0x08 RESERVED.....	96
GYR REGISTER 0x09 (INT_STATUS_0)	96
GYR REGISTER 0x0A (INT_STATUS_1)	97
GYR REGISTER 0x0B (INT_STATUS_2)	97
GYR REGISTER 0x0C (INT_STATUS_3).....	97
GYR REGISTER 0x0D IS RESERVED.....	98

GYR REGISTER 0x0E (FIFO_STATUS).....	98
GYR REGISTER 0x0F (RANGE).....	99
GYR REGISTER 0x10 (BW).....	99
GYR REGISTER 0x11 (LPM1).....	100
GYR REGISTER 0x12 (LPM2).....	101
GYR REGISTER 0x13 (RATE_HBW).....	102
GYR REGISTER 0x14 (BGW_SOFTRESET).....	103
GYR REGISTER 0x15 (INT_EN_0).....	103
GYR REGISTER 0x16 (INT_EN_1).....	104
GYR REGISTER 0x17 (INT_MAP_0).....	104
GYR REGISTER 0x18 (INT_MAP_1).....	104
GYR REGISTER 0x19 (INT_MAP_2).....	105
GYR REGISTER 0x1A.....	106
GYR REGISTER 0x1B.....	106
GYR REGISTER 0x1C.....	106
GYR REGISTER 0x1D IS RESERVED.....	107
GYR REGISTER 0x1E.....	107
GYR REGISTER 0x1F AND 0x20 ARE RESERVED.....	107
GYR REGISTER 0x21 (INT_RST_LATCH).....	108
GYR REGISTER 0x22 (HIGH_TH_X).....	108
GYR REGISTER 0x23 (HIGH_DUR_X).....	109
GYR REGISTER 0x24 (HIGH_TH_Y).....	109
GYR REGISTER 0x25 (HIGH_DUR_Y).....	110
GYR REGISTER 0x26 (HIGH_TH_Z).....	110
GYR REGISTER 0x27 (HIGH_DUR_Z).....	111
GYR REGISTER 0x28 TO 0x30 ARE RESERVED.....	111
GYR REGISTER 0x31 (SOC).....	111
GYR REGISTER 0x32 (A_FOC).....	112
GYR REGISTER 0x33 (TRIM_NVM_CTRL).....	112
GYR REGISTER 0x34 (BGW_SPI3_WDT).....	113
GYR REGISTER 0x35 IS RESERVED.....	113
GYR REGISTER 0x36 (OFC1).....	114
GYR REGISTER 0x37 (OFC2).....	114
GYR REGISTER 0x38 (OFC3).....	115
GYR REGISTER 0x39 (OFC4).....	115
GYR REGISTER 0x3A (TRIM_GP0).....	116
GYR REGISTER 0x3B (TRIM_GP1).....	116
GYR REGISTER 0x3C (BIST).....	117
GYR REGISTER 0x3D (FIFO_CONFIG_0).....	117
GYR REGISTER 0x3E (FIFO_CONFIG_1).....	118

9 FUNCTIONAL DESCRIPTION MAGNETOMETER.....	120
9.1 MAGNETOMETER POWER MANAGEMENT.....	120
9.2 MAGNETOMETER POWER MODES.....	120
9.2.1 POWER OFF MODE.....	120
9.2.2 SUSPEND MODE.....	120
9.2.3 SLEEP MODE.....	120
9.2.4 ACTIVE MODE.....	120
9.3 MAGNETOMETER OUTPUT DATA.....	122
9.3.1 MAGNETIC FIELD DATA.....	122
9.3.2 MAGNETIC FIELD DATA TEMPERATURE COMPENSATION.....	123
9.4 SELF-TEST MAGNETOMETER.....	124

9.4.1	NORMAL SELF TEST	124
9.4.2	ADVANCED SELF TEST	124
9.5	NON-VOLATILE MEMORY	125
9.6	MAGNETOMETER INTERRUPT CONTROLLER	125
9.6.1	GENERAL FEATURES	126
9.6.2	ELECTRICAL BEHAVIOR OF MAGNETIC INTERRUPT PINS	127
9.6.3	DATA READY / DRDY INTERRUPT	127
9.6.4	LOW-THRESHOLD INTERRUPT	127
9.6.5	HIGH-THRESHOLD INTERRUPT	128
9.6.6	OVERFLOW.....	129
10	REGISTER DESCRIPTION MAGNETOMETER	130
10.1	GENERAL REMARKS	130
10.2	REGISTER MAP MAGNETOMETER	130
10.3	CHIP ID MAGNETOMETER	131
	MAG REGISTER (0x40)	131
	MAG REGISTER (0x41) IS RESERVED.....	131
10.4	MAGNETIC FIELD DATA	131
	MAG REGISTER (0x42)	131
	MAG REGISTER (0x43)	131
	MAG REGISTER (0x44)	132
	MAG REGISTER (0x45)	132
	MAG REGISTER (0x46)	132
	MAG REGISTER (0x47)	133
	MAG REGISTER (0x48)	133
	MAG REGISTER (0x49)	133
10.5	INTERRUPT STATUS REGISTER MAGNETOMETER	134
	MAG REGISTER (0x4A).....	134
10.6	POWER AND OPERATION MODES, SELF-TEST, DATA OUTPUT RATE CONTROL REGISTERS	134
	MAG REGISTER (0x4B).....	134
	MAG REGISTER (0x4C).....	135
10.7	INTERRUPT AND AXIS ENABLE SETTINGS CONTROL REGISTERS.....	136
	MAG REGISTER (0x4D).....	136
	MAG REGISTER (0x4E).....	137
	MAG REGISTER (0x4F).....	137
	MAG REGISTER (0x50)	138
10.8	NUMBER OF REPETITIONS CONTROL REGISTERS	138
	MAG REGISTER (0x51)	138
	MAG REGISTER (0x52)	139
11	DIGITAL INTERFACE OF THE DEVICE.....	140
11.1	SERIAL PERIPHERAL INTERFACE (SPI)	141
11.2	INTER-INTEGRATED CIRCUIT (I ² C)	145

11.2.1	SPI AND I ² C ACCESS RESTRICTIONS	149
12	FIFO OPERATION	150
12.1	FIFO OPERATING MODES	150
12.2	FIFO DATA READOUT	151
12.2.1	DATA READOUT ACCELEROMETER.....	151
12.2.2	DATA READOUT GYROSCOPE	152
12.2.3	EXTERNAL FIFO SYNCHRONIZATION (EFS) FOR THE GYROSCOPE	152
12.3	FIFO FRAME COUNTER AND OVERRUN FLAG	153
12.4	FIFO INTERRUPTS	153
13	PIN-OUT AND CONNECTION DIAGRAM	155
13.1	PIN-OUT	155
13.2	CONNECTION DIAGRAM 4-WIRE SPI	157
13.3	CONNECTION DIAGRAM 3-WIRE SPI	158
13.4	CONNECTION DIAGRAM I ² C	159
14	PACKAGE	160
14.1	OUTLINE DIMENSIONS	160
14.2	SENSING AXES ORIENTATION	161
14.3	ANDROID AXES ORIENTATION.....	162
14.4	LANDING PATTERN RECOMMENDATION	164
14.5	MARKING.....	165
14.5.1	MASS PRODUCTION DEVICES	165
14.5.2	ENGINEERING SAMPLES	165
14.6	SOLDERING GUIDELINES	166
14.7	HANDLING INSTRUCTIONS.....	167
14.8	TAPE AND REEL SPECIFICATION.....	168
14.8.1	ORIENTATION WITHIN THE REEL	168
14.9	ENVIRONMENTAL SAFETY	168
14.9.1	HALOGEN CONTENT	169
14.9.2	INTERNAL PACKAGE STRUCTURE	169
15	LEGAL DISCLAIMER	170
15.1	ENGINEERING SAMPLES.....	170
15.2	PRODUCT USE	170
15.3	APPLICATION EXAMPLES AND HINTS	170
16	DOCUMENT HISTORY AND MODIFICATION	171

1 Specification

If not stated otherwise, the given values are over lifetime and full performance temperature and voltage ranges, minimum/maximum values are $\pm 3\sigma$.

1.1 Electrical specification

Table 1: Electrical parameter specification

OPERATING CONDITIONS						
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage Internal Domains	V_{DD}		2.4	3.0	3.6	V
Supply Voltage I/O Domain	V_{DDIO}		1.2	2.4	3.6	V
Voltage Input Low Level	$V_{IL,a}$	SPI & I ² C			$0.3V_{DDIO}$	-
Voltage Input High Level	$V_{IH,a}$	SPI & I ² C	$0.7V_{DDIO}$			-
Voltage Output Low Level	$V_{OL,a}$	$I_{OL} = 3\text{mA}$, SPI & I ² C			$0.23V_{DDIO}$	-
Voltage Output High Level	V_{OH}	$I_{OH} = 3\text{mA}$, SPI	$0.8V_{DDIO}$			-
Operating Temperature	T_A		-40		+85	°C

1.2 Electrical and physical characteristics, measurement performance

Table 2: Electrical characteristics accelerometer

OPERATING CONDITIONS ACCELEROMETER						
Parameter	Symbol	Condition	Min	Typ	Max	Units
Acceleration Range	g_{FS2g}	Selectable via serial digital interface		±2		g
	g_{FS4g}			±4		g
	g_{FS8g}			±8		g
	g_{FS16g}			±16		g
Total Supply Current in Normal Mode	I_{DD}	see ¹		130		μA
Total Supply Current in Suspend Mode	I_{DDsum}	see ¹		2.1		μA
Total Supply Current in Deep Suspend Mode	I_{DDdsum}	see ¹		1.0		μA
Total Supply Current in Low-power Mode 1	I_{DDlp1}	see ¹ sleep duration ≥ 25ms		6.5		μA
Total Supply Current in Low-power Mode 2	I_{DDlp2}	see ¹ sleep duration ≥ 25ms		66		μA
Total Supply Current in Standby Mode	I_{DDsbm}	see ¹		62		μA
Wake-Up Time 1	$t_{w,up1}$	from Low-power Mode 1 or Suspend Mode or Deep Suspend Mode bw = 1kHz		1.3		ms
Wake-Up Time 2	$t_{w,up2}$	from Low-power Mode 2 or Stand-by Mode bw = 1kHz		1		ms
Start-Up Time	$t_{s,up}$	POR, bw = 1kHz				ms
Non-volatile memory (NVM) write-cycles	n_{NVM}				15	Cycles

¹ Conditions of current consumption if not specified otherwise: $T_A=25^{\circ}C$, $BW_Accel=1kHz$, $V_{DD} = V_{DDIO} = 2.4V$, digital protocol on, no streaming data

OUTPUT SIGNAL ACCELEROMETER						
Parameter	Symbol	Condition	Min	Typ	Max	Units
Sensitivity	S_{2g}	$g_{FS2g}, T_A=25^\circ C$		1024		LSB/g
	S_{4g}	$g_{FS4g}, T_A=25^\circ C$		512		LSB/g
	S_{8g}	$g_{FS8g}, T_A=25^\circ C$		256		LSB/g
	S_{16g}	$g_{FS16g}, T_A=25^\circ C$		128		LSB/g
Sensitivity Temperature Drift	TCS	g_{FS2g} , Nominal V_{DD} supplies		± 0.03		%/K
Sensitivity Supply Volt. Drift	S_{VDD}	$g_{FS2g}, T_A=25^\circ C$, $V_{DD \min} \leq V_{DD} \leq V_{DD \max}$		0.05		%/V
Zero-g Offset (x,y,z)	$Off_{x,z}$	$g_{FS2g}, T_A=25^\circ C$, nominal V_{DD} supplies, over life-time		± 80		mg
Zero-g Offset Temperature Drift	TCO	g_{FS2g} , Nominal V_{DD} supplies		± 1		mg/K
Zero-g Offset Supply Volt. Drift	Off_{VDD}	$g_{FS2g}, T_A=25^\circ C$, $V_{DD \min} \leq V_{DD} \leq V_{DD \max}$		0.5		mg/V
Bandwidth	bw_8	2 nd order filter, bandwidth programmable		8		Hz
	bw_{16}			16		Hz
	bw_{31}			31		Hz
	bw_{63}			63		Hz
	bw_{125}			125		Hz
	bw_{250}			250		Hz
	bw_{500}			500		Hz
	bw_{1000}			1,000		Hz
Nonlinearity	NL	best fit straight line, g_{FS2g}	-1	± 0.5	+1	%FS
Output Noise Density	n_{rms}	$g_{FS2g}, T_A=25^\circ C$ Nominal V_{DD} supplies Normal mode		150		$\mu g/\sqrt{Hz}$
Temperature Sensor Measurement Range	T_s		-40		85	$^\circ C$
Temperature Sensor Slope	dT_s			0.5		K/LSB
Temperature Sensor Offset	OT_s			± 2		K

**MECHANICAL CHARACTERISTICS ACCELEROMETER**

Parameter	Symbol	Condition	Min	Typ	Max	Units
Cross Axis Sensitivity	S	relative contribution between any two of the three axes		1		%
Alignment Error	E _A	relative to package outline		±0.5		deg

Table 3: Electrical characteristics gyroscope

OPERATING CONDITIONS GYROSCOPE						
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Range	R _{FS125}	Selectable via serial digital interface		125		°/s
	R _{FS250}			250		°/s
	R _{FS500}			500		°/s
	R _{FS1000}			1,000		°/s
	R _{FS2000}			2,000		°/s
Supply Current in Normal Mode	I _{DD}	see ²		5		mA
Supply Current in Fast Power-up Mode	I _{DDfpm}	see ²		2.5		mA
Supply Current in Suspend Mode	I _{DDsum}	see ² , digital and analog (only IF active)		25		μA
Supply Current in Deep Suspend Mode	I _{DDsum}	see ²		<5		μA
Start-up time	t _{su}	to ±1%/s of final value; from power-off		30		ms
Wake-up time	t _{wusm}	From suspend- and deep suspend-modes		30		ms
Wake-up time	t _{wufpm}	From fast power-up mode		10		ms
Non-volatile memory (NVM) write-cycles	n _{NVM}				15	cycles

² Conditions of current consumption if not specified otherwise: T_A=25°C, BW_Gyro=1kHz, V_{DD}=2.4V, V_{DDIO}=1.8V, digital protocol on, no streaming data

OUTPUT SIGNAL GYROSCOPE						
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Sensitivity		Ta=25°C, R _{FS2000}		16.4		LSB/°/s
		Ta=25°C, R _{FS1000}		32.8		LSB/°/s
		Ta=25°C, R _{FS500}		65.6		LSB/°/s
		Ta=25°C, R _{FS250}		131.2		LSB/°/s
		Ta=25°C, R _{FS125}		262.4		LSB/°/s
Sensitivity tolerance		Ta=25°C, R _{FS2000}		±1		%
Sensitivity Change over Temperature	TCS	Nominal V _{DD} supplies -40°C ≤ T _A ≤ +85°C R _{FS2000}		±0.03		%/K
Sensitivity Supply Volt. Drift	S _{VDD}	T _A =25°C, V _{DD_min} ≤ V _{DD} ≤ V _{DD_max}		<0.4		%/V
Nonlinearity	NL	best fit straight line R _{FS1000} , R _{FS2000}		±0.05		%FS
g- Sensitivity		Sensitivity to acceleration stimuli in all three axis (frequency <20kHz)			0.1	°/s/g
Zero-rate Offset	Off Ω _x Ω _y and Ω _z	Nominal V _{DD} supplies T _A =25°C, slow and fast offset cancellation off		±1		°/s
Zero-Ω Offset Change over Temperature	TCO	Nominal V _{DD} supplies -40°C ≤ T _A ≤ +85°C R _{FS2000}		±0.015		°/s per K
Zero-Ω Offset Supply Volt. Drift	OffΩ _{VDD}	T _A =25°C, V _{DD_min} ≤ V _{DD} ≤ V _{DD_max}		<0.1		°/s /V
Output Noise	n _{rms}	rms, BW=47Hz (@ 0.014°/s/√Hz)		0.1		°/s



Bandwidth BW	f_{-3dB}			unfiltered 230 116 64 47 32 23 12		Hz
Data rate (set of x,y,z rate)				2000 1000 400 200 100		Hz
Data rate tolerance (set of x,y,z rate)				±0.3		%
Cross Axis Sensitivity		Sensitivity to stimuli in non-sense-direction		±1		%

Table 4: Electrical characteristics magnetometer

OPERATING CONDITIONS MAGNETOMETER						
Parameter	Symbol	Condition	Min	Typ	Max	Units
Magnetic field range ³	Brg,xy	TA=25°C	±1200	±1300		μT
	Brg,z		±2000	±2500		μT
Magnetometer heading accuracy ⁴	AC _{heading}	30μT horizontal geomagnetic field component, TA=25°C			±2.5	deg
System heading accuracy ⁵	AS _{heading}	30μT horizontal geomagnetic field component, TA=25°C			±3.0	deg
Supply Current in Active Mode (average) ⁶	IDD,lp,m	Low power preset Nominal VDD supplies TA=25°C, ODR=10Hz		170		μA
	IDD,rg,m	Regular preset Nominal VDD supplies TA=25°C, ODR=10Hz		0.5		mA
	IDD,eh,m	Enhanced regular preset Nominal VDD supplies TA=25°C, ODR=10Hz		0.8		mA
	IDD,ha,m	High accuracy preset Nominal VDD supplies TA=25°C, ODR=20Hz		4.9		mA
Supply Current in Suspend Mode	IDDsm,m	Nominal VDD/VDDIO supplies, TA=25°C		1		μA
Peak supply current in Active Mode	IDDpk,m	In measurement phase Nominal VDD supplies TA=25°C		18		mA
Peak logic supply current in active mode	IDDIOpk,m	Only during measurement phase Nominal VDDIO supplies TA=25°C		210		μA
POR time	tw _{up} ,m	from OFF to Suspend; time starts when VDD>1.5V and VDDIO>1.1V			1.0	ms
Start-Up Time	ts _{up} ,m	from Suspend to sleep			3.0	ms

³ Full linear measurement range considering sensor offsets.

⁴ The heading accuracy depends on hardware and software. For detailed information of the software performance please contact Bosch Sensortec.

⁵ Heading accuracy of the tilt-compensated 9-axis system, assuming calibration with Bosch Sensortec FusionLib software. Average value over various device orientations (typical device usage).

⁶ For details on magnetometer current consumption calculation refer to chapter 9.2.4

MAGNETOMETER OUTPUT SIGNAL						
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Device Resolution	$D_{res,m}$	$T_A=25^\circ\text{C}$		0.3		μT
Gain error ⁷	$G_{err,m}$	After API compensation $T_A=25^\circ\text{C}$ Nominal V_{DD} supplies		± 5		%
Sensitivity Temperature Drift	TCS_m	After API compensation $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$ Nominal V_{DD} supplies		± 0.01		%/K
Zero-B offset	OFF_m	$T_A=25^\circ\text{C}$		± 40		μT
Zero-B offset ⁸	$OFF_{m,cal}$	After software calibration with Bosch Sensortec eCompass software $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$		± 2		μT
ODR (data output rate), normal mode	odr_{lp}	Low power preset		10		Hz
	odr_{rg}	Regular preset		10		Hz
	odr_{eh}	Enhanced regular preset		10		Hz
	odr_{ha}	High accuracy preset		20		Hz
ODR (data output rate), forced mode	odr_{lp}	Low power preset	0		>300	Hz
	odr_{rg}	Regular preset	0		100	Hz
	odr_{eh}	Enhanced regular preset	0		60	Hz
	odr_{ha}	High accuracy preset	0		20	Hz
Full-scale Nonlinearity	$NL_{m,FS}$	best fit straight line			1	%FS
Output Noise	$n_{rms,lp,m,xy}$	Low power preset x, y-axis, $T_A=25^\circ\text{C}$ Nominal V_{DD} supplies		1.0		μT
	$n_{rms,lp,m,z}$	Low power preset z-axis, $T_A=25^\circ\text{C}$ Nominal V_{DD} supplies		1.4		μT
	$n_{rms,rg,m}$	Regular preset $T_A=25^\circ\text{C}$ Nominal V_{DD} supplies		0.6		μT
	$n_{rms,eh,m}$	Enhanced regular preset $T_A=25^\circ\text{C}$ Nominal V_{DD} supplies		0.5		μT

⁷ Definition: $gain\ error = (measured\ field\ after\ API\ compensation) / (applied\ field) - 1$

⁸ Magnetic zero-B offset assuming calibration with Bosch Sensortec eCompass software. Typical value after applying calibration movements containing various device orientations (typical device usage).



	$n_{\text{rms,ha,m}}$	High accuracy preset $T_A=25^\circ\text{C}$ Nominal V_{DD} supplies		0.3		μT
Power Supply Rejection Rate	PSRR _m	$T_A=25^\circ\text{C}$ Nominal V_{DD} supplies		± 0.5		$\mu\text{T/V}$

2 Absolute maximum ratings

Table 5: Absolute maximum ratings

Parameter	Condition	Min	Max	Units
Voltage at Supply Pin	V_{DD} Pin	-0.3	4.25	V
	V_{DDIO} Pin	-0.3	4.25	V
Voltage at any Logic Pin	Non-Supply Pin	-0.3	$V_{DDIO}+0.3$	V
Passive Storage Temp. Range	$\leq 65\%$ rel. H.	-50	+150	$^{\circ}\text{C}$
None-volatile memory (NVM) Data Retention	$T = 85^{\circ}\text{C}$, after 15 cycles	10		y
Mechanical Shock	Duration $\leq 200\mu\text{s}$		10,000	g
	Duration $\leq 1.0\text{ms}$		2,000	g
	Free fall onto hard surfaces		1.8	m
ESD	HBM, at any Pin		2	kV
	CDM		500	V
	MM		200	V

Note: Stress above these limits may cause damage to the device. Exceeding the specified electrical limits may affect the device reliability or cause malfunction.

3 Block diagram

Figure 1 shows the basic building blocks of the BMX055:

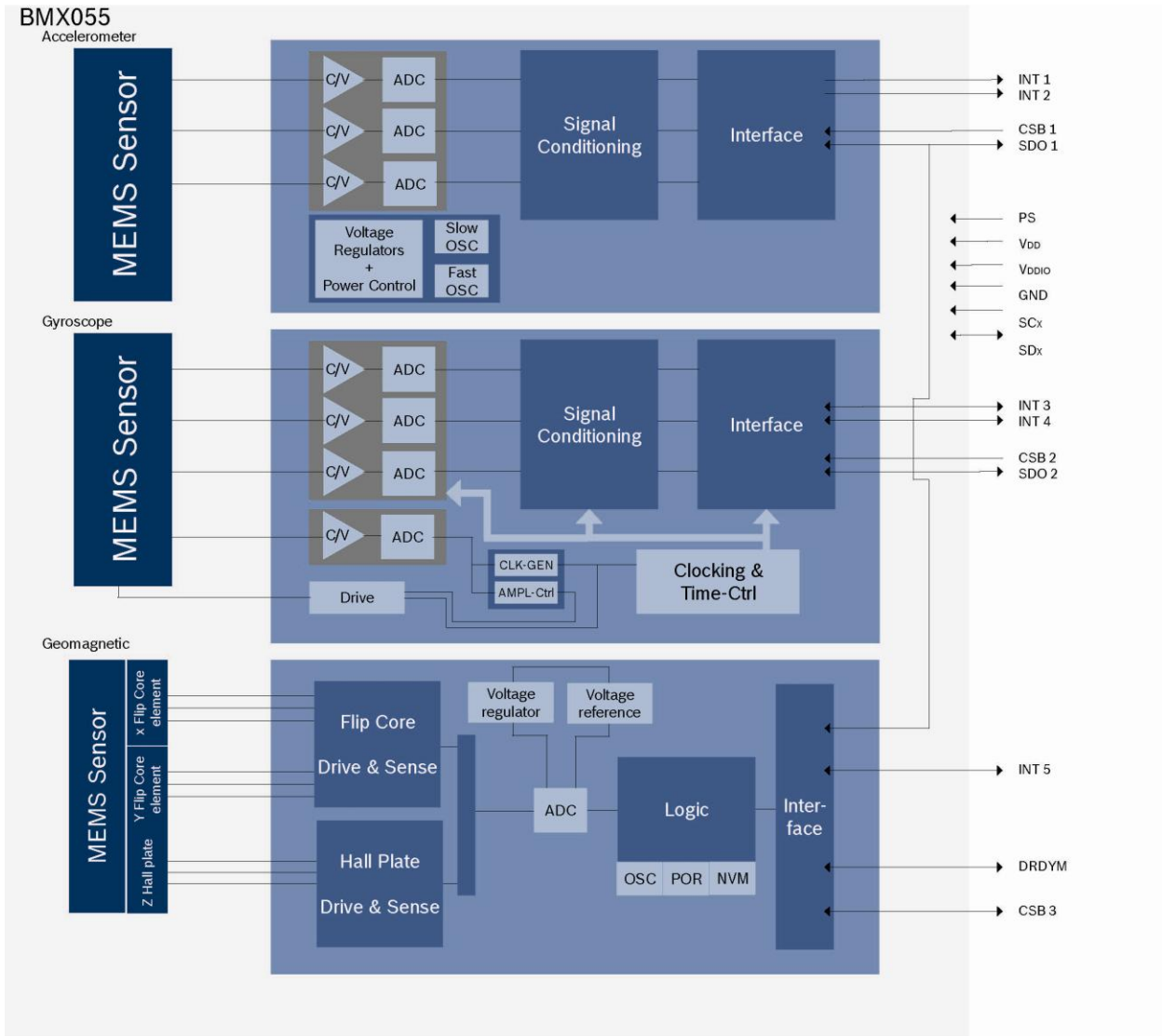


Figure 1: Block diagram of the BMX055

4 Basic power management

The BMX055 has two distinct power supply pins:

- V_{DD} is the main power supply for the internal blocks
- V_{DDIO} is a separate power supply pin mainly used for the supply of the interface

There are no limitations on the voltage levels of both pins relative to each other, as long as each of them lies within its operating range. Furthermore, the device can be completely switched off ($V_{DD} = 0V$) while keeping the V_{DDIO} supply on ($V_{DDIO} > 0V$) or vice versa.

When the V_{DDIO} supply is switched off, all interface pins (CSB, SDI, SCK, PS) must be kept close to GND_{IO} potential.

The device contains a power-on reset (POR) generator. It resets the logic part and the register values after powering-on V_{DD} and V_{DDIO} . Please note, that all application specific settings which are not equal to the default settings (refer to 6.2 register map accelerometer, to 8.2 register map gyroscope and to 10.2 register map magnetometer), must be re-set to its designated values after POR.

In case the I²C interface shall be used, a direct electrical connection between V_{DDIO} supply and the PS pin is needed in order to ensure reliable protocol selection. For SPI interface mode the PS pin must be directly connected to GND_{IO} .

5 Functional description accelerometer

Note: Default values for registers can be found in Chapter 6.

5.1 Acceleration data

The accelerometer has six different power modes. Besides normal mode, which represents the fully operational state of the device, there are five energy saving modes: deep-suspend mode, suspend mode, standby mode, low-power mode 1 and low-power mode 2.

The possible transitions between the power modes are illustrated in Figure 2:

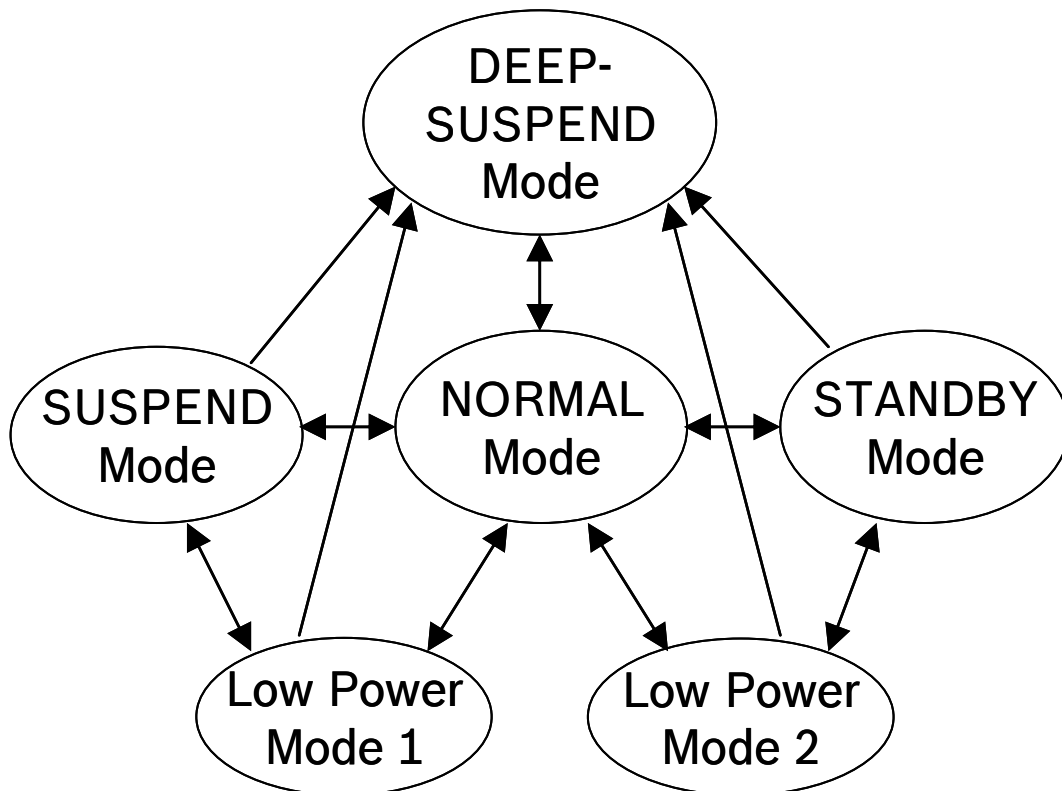


Figure 2: Power mode transition diagram

After power-up accelerometer is in normal mode so that all parts of the device are held powered-up and data acquisition is performed continuously.

In **deep-suspend** mode the device reaches the lowest possible power consumption. Only the interface section is kept alive. No data acquisition is performed and the content of the configuration registers is lost. Deep suspend mode is entered (left) by writing '1' ('0') to the (ACC 0x11) *deep_suspend* bit while (ACC 0x11) *suspend* bit is set to '0'. The I²C watchdog timer remains functional. The (ACC 0x11) *deep_suspend* bit, the (ACC 0x34) *spi3* bit, (ACC 0x34) *i2c_wdt_en* bit and the (ACC 0x34) *i2c_wdt_sel* bit are functional in deep-suspend mode. Equally the interrupt level and driver configuration registers (ACC 0x20) *int1_lvl*, (ACC 0x20) *int1_od*, (ACC 0x20) *int2_lvl*, and (ACC 0x20) *int2_od* are accessible. Still it is possible to enter normal mode by performing a softreset as described in chapter 5.7. Please note, that all

application specific settings which are not equal to the default settings (refer to 6.2 register map accelerometer), must be re-set to its designated values after leaving deep-suspend mode.

In **suspend mode** the whole analog part is powered down. No data acquisition is performed. While in suspend mode the latest acceleration data and the content of all configuration registers are kept. Writing to and reading from registers is supported except from the (0x3E) `fifo_config_1`, (0x30) `fifo_config_0` and (0x3F) `fifo_data` register. It is possible to enter normal mode by performing a softreset as described in chapter 5.7.

Suspend mode is entered (left) by writing '1' ('0') to the (ACC 0x11) `suspend` bit after bit (ACC 0x12) `lowpower_mode` has been set to '0'. Although write access to registers is supported at the full interface clock speed (SCL or SCK), a waiting period must be inserted between two consecutive write cycles (please refer also to section 9.2.1).

In **standby mode** the analog part is powered down, while the digital part remains largely operational. No data acquisition is performed. Reading and writing registers is supported without any restrictions. The latest acceleration data and the content of all configuration registers are kept. Standby mode is entered (left) by writing '1' ('0') to the (ACC 0x11) `suspend` bit after bit (ACC 0x12) `lowpower_mode` has been set to '1'. It is also possible to enter normal mode by performing a softreset as described in chapter 5.7.

In **low-power mode 1**, the device is periodically switching between a sleep phase and a wake-up phase. The wake-up phase essentially corresponds to operation in normal mode with complete power-up of the circuitry. The sleep phase essentially corresponds to operation in suspend mode. Low-power mode is entered (left) by writing '1' ('0') to the (ACC 0x11) `lowpower_en` bit with bit (ACC 0x12) `lowpower_mode` set to '0'. Read access to registers is possible except from the (0x3F) `fifo_data` register. However, unless the register access is synchronised with the wake-up phase, the restrictions of the suspend mode apply.

Low-power mode 2 is very similar to low-power mode 1, but register access is possible at any time without restrictions. It consumes more power than low-power mode 1. In low-power mode 2 the device is periodically switching between a sleep phase and a wake-up phase. The wake-up phase essentially corresponds to operation in normal mode with complete power-up of the circuitry. The sleep phase essentially corresponds to operation in standby mode. Low-power mode is entered (left) by writing '1' ('0') to the (ACC 0x11) `lowpower_en` bit with bit (ACC 0x12) `lowpower_mode` set to '1'.

The timing behaviour of the low-power modes 1 and 2 depends on the setting of the (ACC 0x12) `sleeptimer_en` bit. When (ACC 0x12) `sleeptimer_en` is set to '0', the event-driven time-base mode (EDT) is selected. In EDT the duration of the wake-up phase depends on the number of samples required by the enabled interrupt engines. If an interrupt is detected, the device stays in the wake-up phase as long as the interrupt condition endures (non-latched interrupt), or until the latch time expires (temporary interrupt), or until the interrupt is reset (latched interrupt). If no interrupt is detected, the device enters the sleep phase immediately after the required number of acceleration samples have been taken and an active interface access cycle has ended. The EDT mode is recommended for power-critical applications which do not use the FIFO. Also, EDT mode is compatible with legacy BST sensors. Figure 3 shows the timing diagram for low-power modes 1 and 2 when EDT is selected.

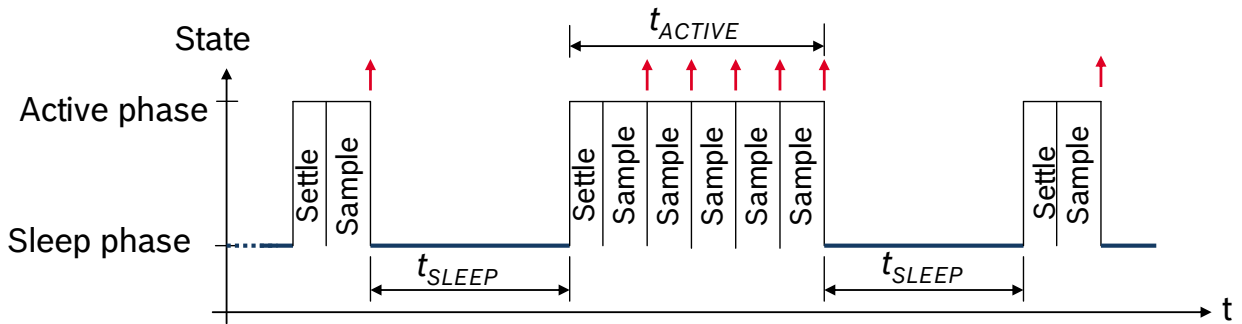


Figure 3: Timing Diagram for low-power mode 1/2, EDT

When (*ACC 0x12*) *sleeptimer_en* is set to '1', the equidistant-sampling mode (EST) is selected. The use of the EST mode is recommended when the FIFO is used since it ensures that equidistant samples are sampled into the FIFO regardless of whether the active phase is extended by active interrupt engines or interface activity. In EST mode the sleep time t_{SLEEP} is defined as shown in Figure 4. The FIFO sampling time t_{SAMPLE} is the sum of the sleep time t_{SLEEP} and the sensor data sampling time t_{SSMP} . Since interrupt engines can extend the active phase to exceed the sleep time t_{SLEEP} , equidistant sampling is only guaranteed if the bandwidth has been chosen such that $1/(2 * bw) = n * t_{SLEEP}$ where n is an integer. If this condition is infringed, equidistant sampling is not possible. Once the sleep time has elapsed the device will store the next available sample in the FIFO. This set-up condition is not recommended as it may result in timing jitter.

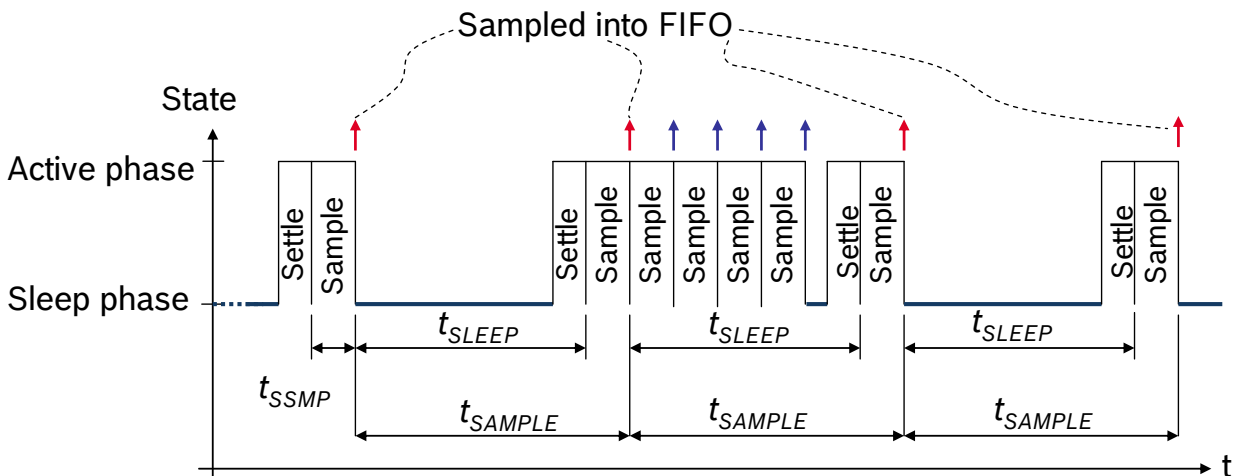


Figure 4: Timing Diagram for low-power mode 1/2, EST